

Please amend the claims as follows. This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-24 (cancelled)

Claim 25 (previously amended): A polishing pad conditioner for use in a chemical mechanical polishing (CMP) apparatus, comprising:

a fixed abrasive polishing pad having an abrasive polishing surface;

a web dressing media having a contact surface defined between a first point and a second point, the first point being separate from the second point, wherein the web dressing media is configured to be positioned over the fixed abrasive polishing pad such that the contact surface of the web dressing media is configured to be applied to the abrasive polishing surface of the fixed abrasive polishing pad;

a pressure application plate configured to be applied against an application surface of the web dressing media that is an opposite surface to the contact surface and is defined between a first position and a second position of the application surface of the web dressing media;

a feed-roll positioned above the fixed abrasive polishing pad, the feed-roll being configured to have a supply of the web dressing media, the feed-roll is positioned at about the first point; and

a take-up roll positioned above the fixed abrasive polishing pad, the take-up roll being configured to collect at least a linear portion of the web dressing media, the take-up roll is positioned at about the second point,

wherein the dressing media, the feed-roll, and the take-up roll define a web handling system, the web handling system being enclosed in a housing configured to rotate.

Claim 26 (previously amended): A polishing pad conditioner for use in a chemical mechanical polishing (CMP) apparatus, comprising:

a fixed abrasive polishing pad having an abrasive polishing surface;

a web dressing media having a contact surface defined between a first point and a second point, the first point being separate from the second point, wherein the web dressing media is configured to be positioned over the fixed abrasive polishing pad such that the contact surface of the web dressing media is configured to be applied to the abrasive polishing surface of the fixed abrasive polishing pad; and

a pressure application plate configured to be applied against an application surface of the web dressing media that is an opposite surface to the contact surface and is defined between a first position and a second position,

wherein the web dressing media and the pressure application plate are enclosed in a housing configured to rotate.

Claims 27-41 (cancelled)

Claim 42 (previously added): A polishing pad conditioner as recited in claim 25, further comprising:

a stabilization member for controllably applying the pressure application plate to the web dressing media so as to apply the web dressing media to the surface of the polishing pad.

Claim 43 (previously added): A polishing pad conditioner as recited in claim 26, further comprising:

a feed-roll positioned above the fixed abrasive polishing pad, the feed-roll being configured to have a supply of the web dressing media, the feed-roll being positioned at about the first point; and

a take-up roll positioned above the fixed abrasive polishing pad, the take-up roll being configured to collect at least a linear portion of the web dressing media, the take-up roll being positioned at about the second point.

Claims 44-57 (cancelled)

Claim 58 (previously added): A polishing pad conditioner for use in a chemical mechanical polishing (CMP) apparatus, comprising:

a web dressing media defined between a first point and a second point, the first point being separate from the second point, the web dressing media having an application surface and a contact surface, the application surface being an opposite surface to the contact surface;

a pressure application member configured to be applied against the application surface of the web dressing media causing the contact surface of the web dressing media defined opposite to the portion of the application surface to be applied onto a pad surface;

a feed-roll configured to have a supply of the web dressing media, the feed-roll being positioned at about the first point; and

a take-up roll configured to collect at least a linear portion of the web dressing media, the take-up roll being positioned at about the second point,

wherein the web dressing media, the feed-roll, and the take-up roll define a web handling system, the web handling system configured to rotate.

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Reply to Final Office action of January 14, 2004 and the Advisory Action of April 6, 2004

Claim 59 (previously added): A polishing pad conditioner as recited in claim 58, wherein the pressure application member can be one of a plate, a disk, and a roller.